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 **IEEE IEEE ICMA 2020****2020 IEEE International Conference on  
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The 2020 IEEE International Conference on Mechatronics and Automation (IEEE ICMA 2020) will take place in Beijing, China from October 13 to October 16, 2020. Beijing is both a tribute to China's proud history and a gateway to China's future. The capital city during the Liao, Yuan, Ming and Qing Dynasties, Beijing has long been the political, cultural, and diplomatic center of China. It is now an international metropolis, home to 11 million people from all walks of life.

As the host city of IEEE ICMA 2020, Beijing not only provides the attendees with a great venue for this event, but also an unparalleled experience in Chinese history and culture. You are cordially invited to join us at IEEE ICMA 2020 in Beijing. The objective of ICMA 2020 is to provide a forum for researchers, educators, engineers, and government officials involved in the general areas of mechatronics, robotics, automation and sensors to disseminate their latest research results and exchange views on the future research directions of these fields.

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**Important Dates:**

**June 10, 2020** Full papers and organized session proposals  
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**July 15, 2020** Notification of paper and session acceptance  
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